

APS-03-002



December 17, 2003

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/682,054 10/09/03 |
Kim Hwee Tan et al.
PILLAR STRUCTURES
| ----- |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on December 19, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date SB Ackerman 12/19/03

"Advanced Connections," Spring 2002, Advanced Interconnect Technologies, issue describes, inter alia, a pillar bumping interconnect technology that uses perimeter or array flip-chip pads to connect an integrated circuit (IC) to a copper lead frame.

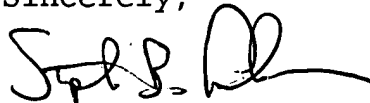
U.S. Patent 6,550,666 to Chew et al., "Method for Forming a Flip Chip on Leadframe Semiconductor Package," discloses a method for forming a flip chip on leadframe semiconductor package.

U.S. Patent 5,448,114 to Kondoh et al., "Semiconductor Flipchip Packaging Having a Perimeter Wall," discloses a semiconductor flip chip packaging having a perimeter wall.

U.S. Patent 6,297,551 to Dudderar et al., "Integrated Circuit Packages with Improved EMI Characteristics," discloses integrated circuit packages with improved EMI characteristics.

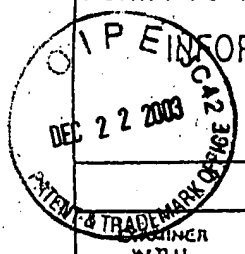
U.S. Patent 4,430,690 to Chance et al., "Low Inductance MLC Capacitor with Metal Impregnation and Solder Bar Contact," discloses a low inductance capacitor with metal impregnation and solder bar contact.

Sincerely,

A handwritten signature in black ink, appearing to read "Stephen B. Ackerman".

Stephen B. Ackerman,
Reg. No. 37761

1 of 1



Form PTO-1449

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION
(Use several sheets if necessary)

Doclet Number (Optional)

APS-03-002

Application Number

10/682,054

Applicant

Kim Hwee Tan et al.

Filing Date

10/09/03

Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	6550666	4/22/03	Chew et al.	228	180.22	8/21/01
	5448114	9/5/95	Kondoh et al.	257	778	2/15/95
	6297581	10/2/01	Dudderar et al.	257	723	9/22/99
	4430690	2/7/84	Chance et al.	361	321	10/7/82

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

	"Advanced Connections," Spring 2002, Advanced Interconnect Technologies, pp. 1-8.

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.